

# BTA204S-1000C

3Q Hi-Com Triac

Rev. 1 — 6 June 2011

Product data sheet

## 1. Product profile

### 1.1 General description

Planar passivated high commutation three quadrant triac in a SOT428 (DPAK) surface-mountable plastic package intended for use in circuits where high static and dynamic  $dV/dt$  and high  $dI/dt$  can occur. This "series C" triac will commute the full rated RMS current at the maximum rated junction temperature without the aid of a snubber.

### 1.2 Features and benefits

- 3Q technology for improved noise immunity
- High blocking voltage capability
- High commutation capability with maximum false trigger immunity
- High immunity to false turn-on by  $dV/dt$
- Less sensitive gate for high noise immunity
- Planar passivated for voltage ruggedness and reliability
- Surface-mountable package
- Triggering in three quadrants only

### 1.3 Applications

- General purpose motor control circuits
- Home appliances
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	-	1000	V
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 20\text{ ms}$ ; see <a href="#">Figure 4</a> ; see <a href="#">Figure 5</a>	-	-	25	A
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 107\text{ }^{\circ}\text{C}$ ; see <a href="#">Figure 1</a> ; see <a href="#">Figure 2</a> ; see <a href="#">Figure 3</a>	-	-	4	A

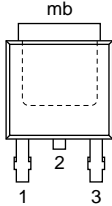



**Table 1. Quick reference data ...continued**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T2+ G+;$ $T_j = 25\text{ }^\circ\text{C};$ see <a href="#">Figure 7</a>	2	6	35	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T2+ G-;$ $T_j = 25\text{ }^\circ\text{C};$ see <a href="#">Figure 7</a>	2	8	35	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T2- G-;$ $T_j = 25\text{ }^\circ\text{C};$ see <a href="#">Figure 7</a>	2	20	35	mA

## 2. Pinning information

**Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		 sym051
2	T2	main terminal 2 <sup>[1]</sup>		
3	G	gate		
mb	T2	mounting base; main terminal 2		

**SOT428 (DPAK)**

[1] It is not possible to connect to pin 2 of the SOT428 package.

## 3. Ordering information

**Table 3. Ordering information**

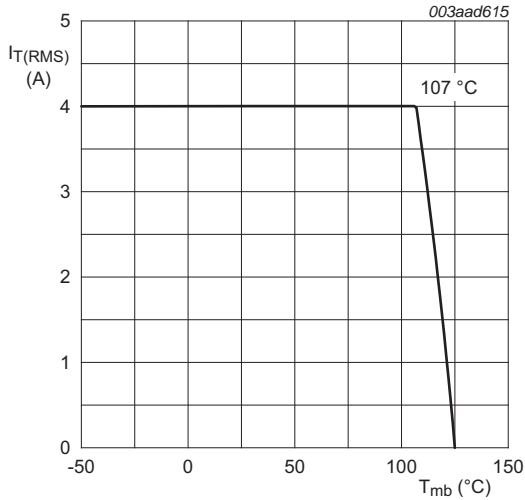
Type number	Package		Version
	Name	Description	
BTA204S-1000C	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

## 4. Limiting values

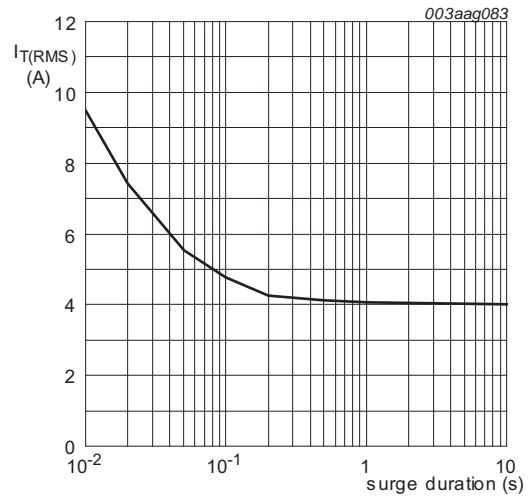
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	1000	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 107\text{ °C}$ ; see <a href="#">Figure 1</a> ; see <a href="#">Figure 2</a> ; see <a href="#">Figure 3</a>	-	4	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ; see <a href="#">Figure 4</a> ; see <a href="#">Figure 5</a>	-	25	A
		full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 16.7\text{ ms}$	-	27	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; sine-wave pulse	-	3.1	A <sup>2</sup> s
$dI_T/dt$	rate of rise of on-state current	$I_T = 6\text{ A}$ ; $I_G = 0.2\text{ A}$ ; $dI_G/dt = 0.2\text{ A}/\mu\text{s}$	-	100	A/ $\mu\text{s}$
$I_{GM}$	peak gate current		-	2	A
$P_{GM}$	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
$T_{stg}$	storage temperature		-40	150	°C
$T_j$	junction temperature		-	125	°C



**Fig 1. RMS on-state current as a function of mounting base temperature; maximum values**



$f = 50\text{ Hz}$ ;  $T_{mb} = 107\text{ °C}$

**Fig 2. RMS on-state current as a function of surge duration; maximum values**

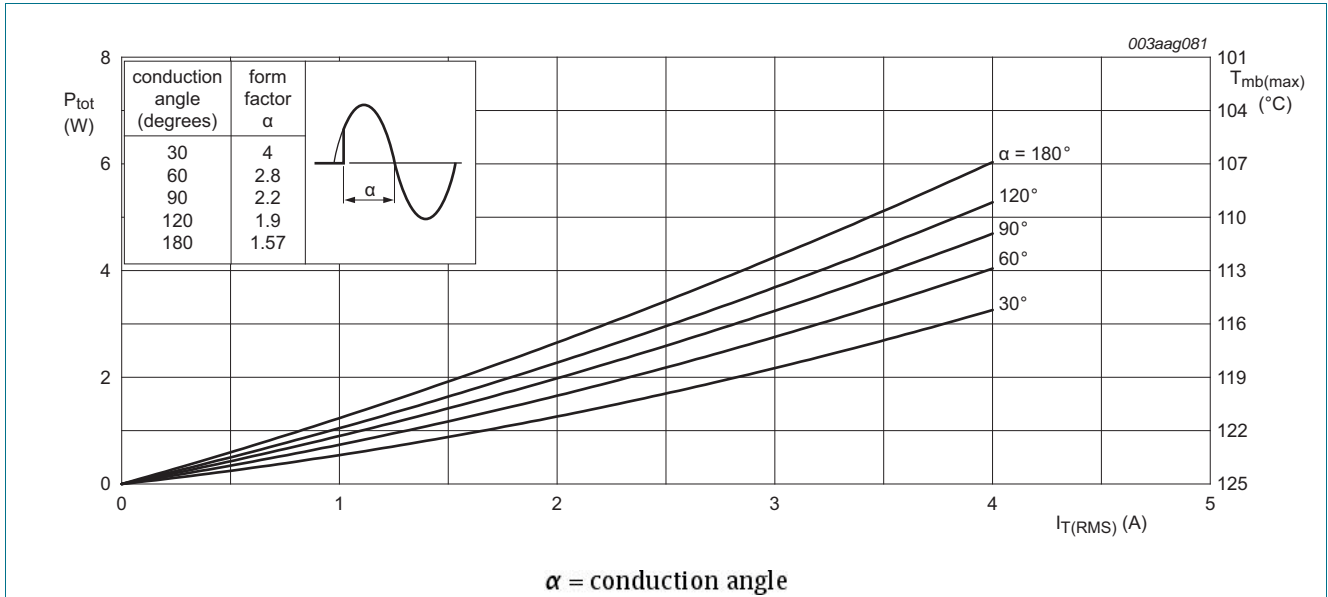


Fig 3. Total power dissipation as a function of RMS on-state current; maximum values

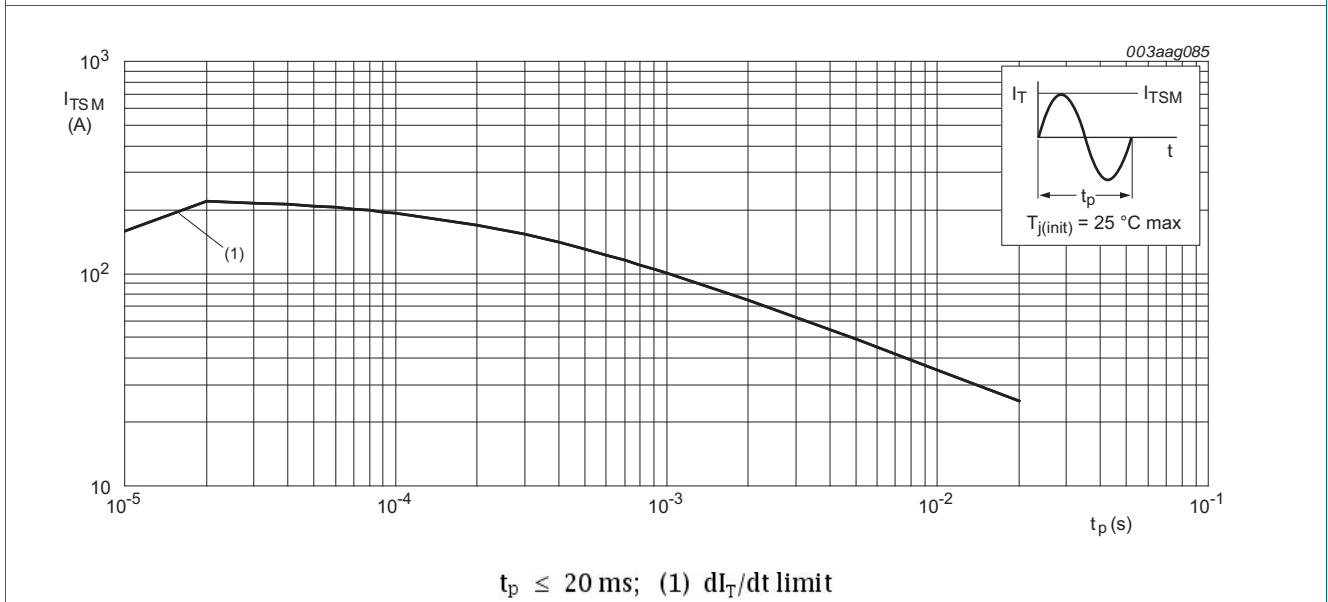
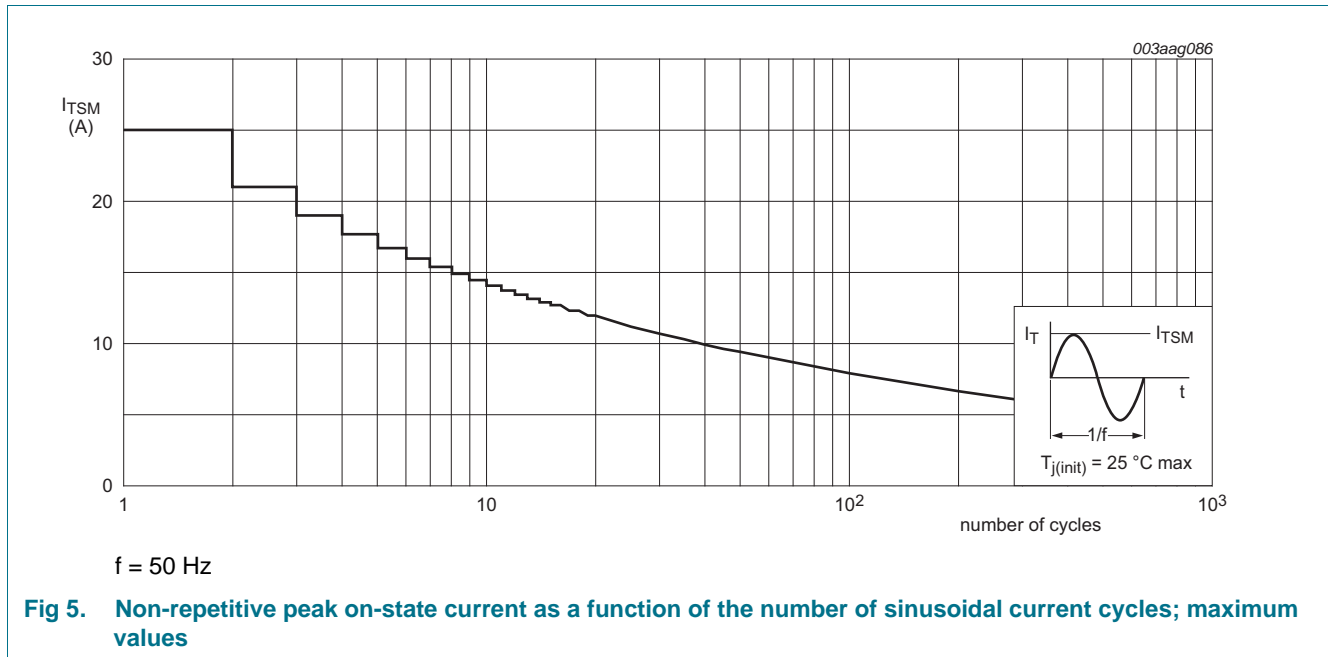


Fig 4. Non-repetitive peak on-state current as a function of pulse width; maximum values

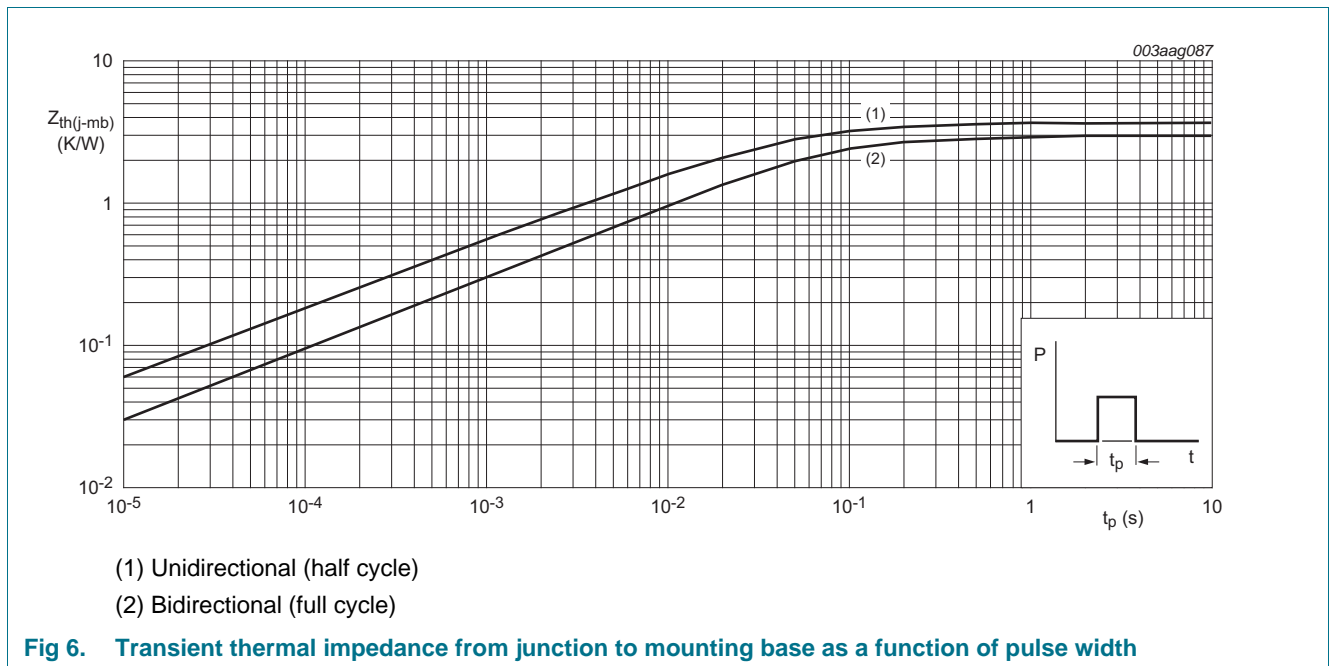


## 5. Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; see <a href="#">Figure 6</a>	-	-	3	K/W
		half cycle; see <a href="#">Figure 6</a>	-	-	3.7	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	75	K/W

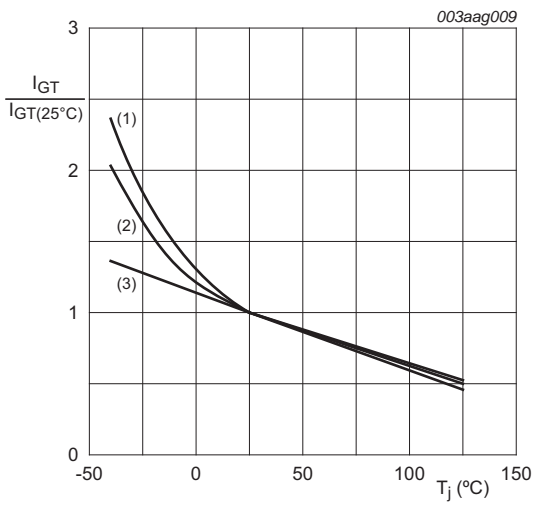
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



## 6. Characteristics

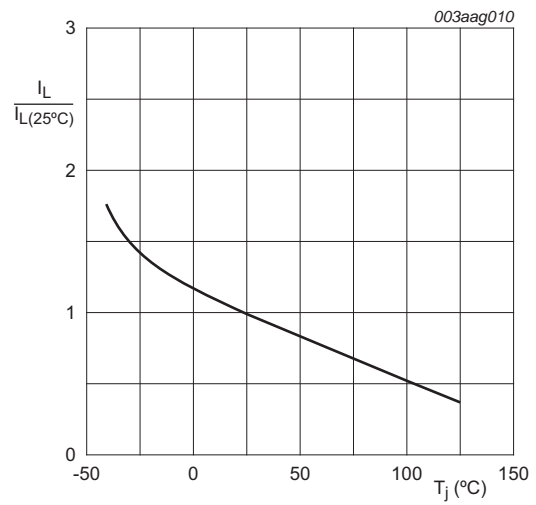
Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 7</a>	2	6	35	mA
		$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 7</a>	2	8	35	mA
		$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 7</a>	2	20	35	mA
$I_L$	latching current	$V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G+; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 8</a>	-	-	20	mA
		$V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G-; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 8</a>	-	-	30	mA
		$V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G-; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 8</a>	-	-	20	mA
$I_H$	holding current	$V_D = 12\text{ V}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 9</a>	-	-	20	mA
$V_T$	on-state voltage	$I_T = 5\text{ A}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 10</a>	-	1.4	1.7	V
$V_{GT}$	gate trigger voltage	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 11</a>	-	0.7	1.5	V
		$V_D = 400\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 125\text{ °C}$ ; see <a href="#">Figure 11</a>	0.25	0.4	-	V
$I_D$	off-state current	$V_D = 1000\text{ V}$ ; $T_j = 125\text{ °C}$	-	0.1	0.5	mA
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 670\text{ V}$ ; $T_j = 125\text{ °C}$ ; exponential waveform; gate open circuit	1000	1500	-	V/ $\mu$ s
$di_{com}/dt$	rate of change of commutating current	$V_D = 400\text{ V}$ ; $T_j = 125\text{ °C}$ ; $I_{T(RMS)} = 4\text{ A}$ ; $dV_{com}/dt = 20\text{ V}/\mu$ s; snubberless condition; gate open circuit	3	30	-	A/ms
$t_{gt}$	gate-controlled turn-on time	$I_{TM} = 12\text{ A}$ ; $V_D = 1000\text{ V}$ ; $I_G = 0.1\text{ A}$ ; $di_G/dt = 5\text{ A}/\mu$ s	-	2	-	$\mu$ s

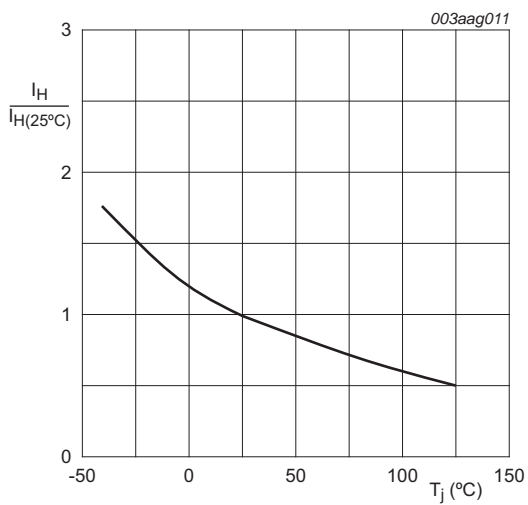


- (1) T2 - G -
- (2) T2 + G -
- (3) T2 + G +

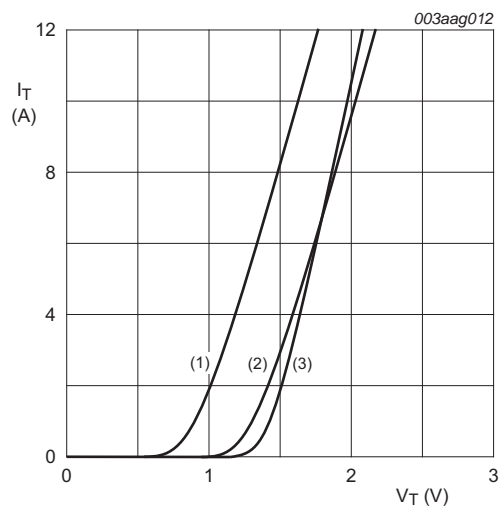
**Fig 7. Normalized gate trigger current as a function of junction temperature**



**Fig 8. Normalized latching current as a function of junction temperature**



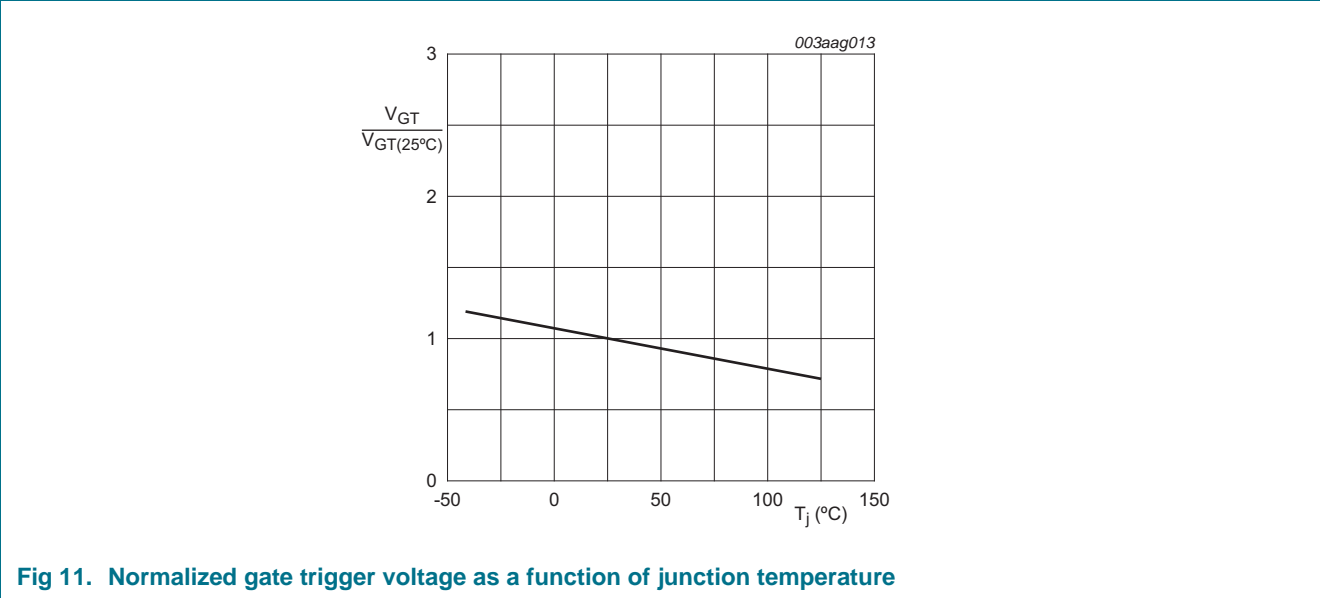
**Fig 9. Normalized holding current as a function of junction temperature**



- $V_o = 1.22 \text{ V}; R_s = 0.04 \Omega$
- (1)  $T_j = 125 \text{ }^\circ\text{C}$ ; typical values
  - (2)  $T_j = 125 \text{ }^\circ\text{C}$ ; maximum values
  - (3)  $T_j = 25 \text{ }^\circ\text{C}$ ; maximum values

**Fig 10. On-state current as a function of on-state voltage**





**7. Package outline**

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)

SOT428

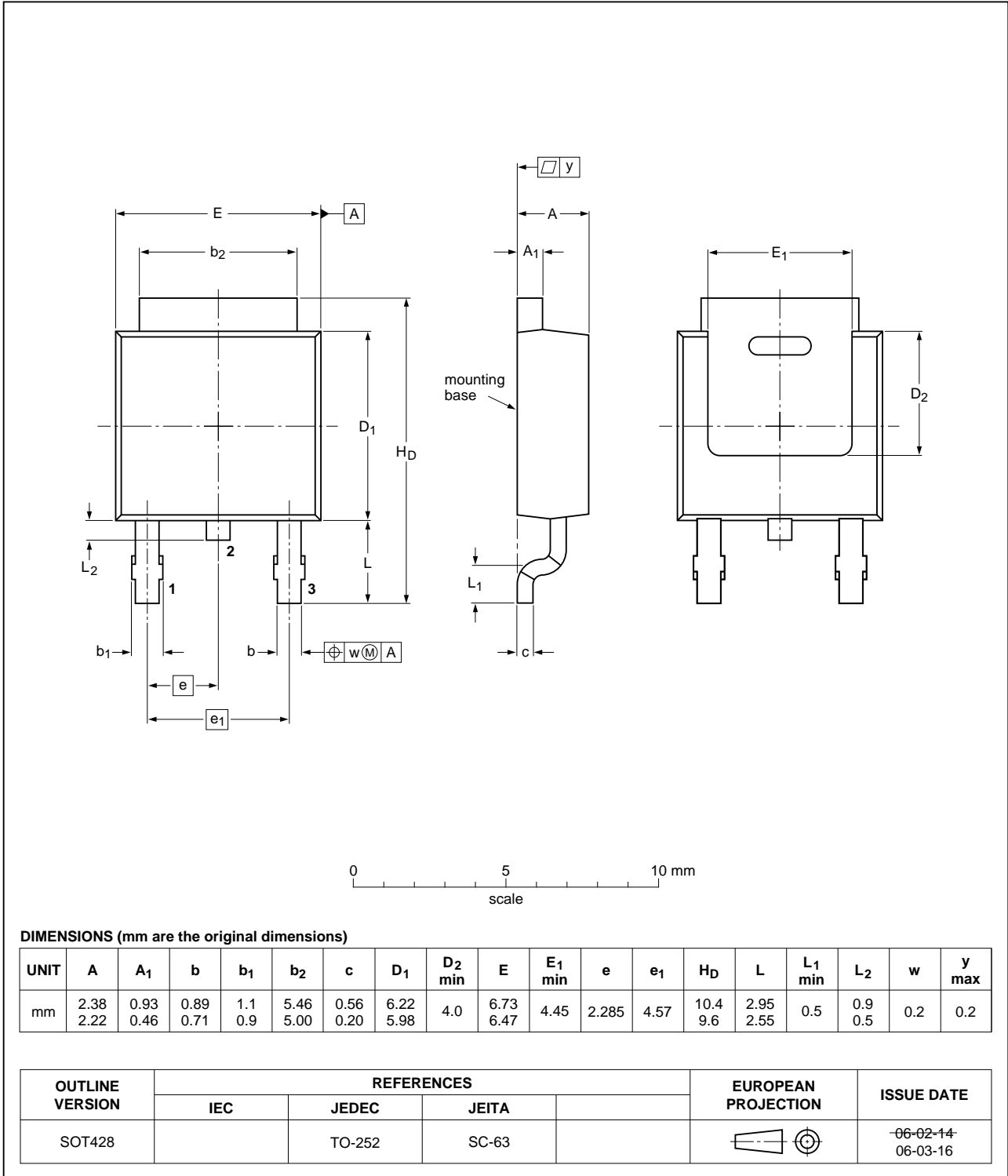
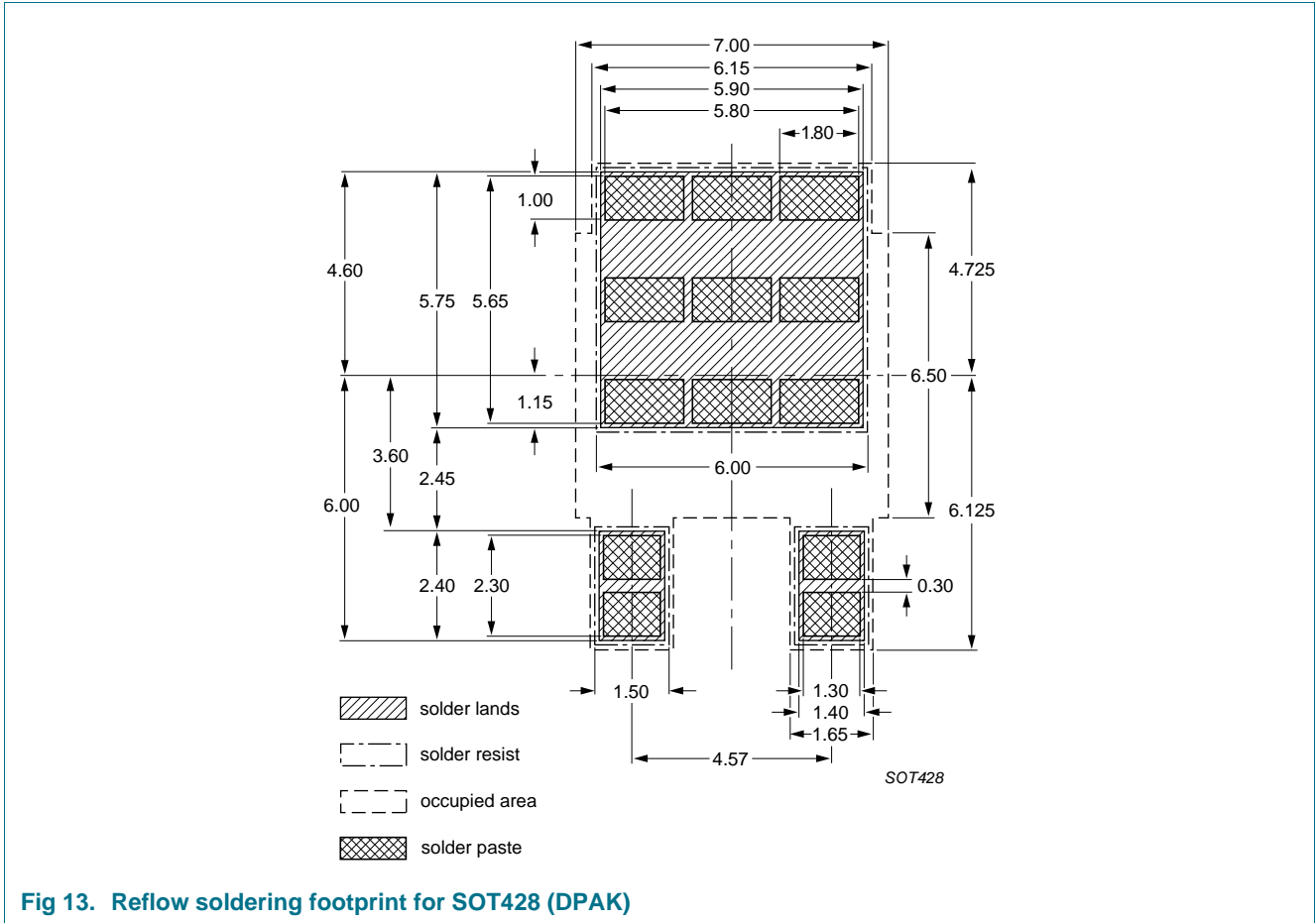


Fig 12. Package outline SOT428 (DPAK)

**8. Soldering**



**Fig 13. Reflow soldering footprint for SOT428 (DPAK)**

## 9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BTA204S-1000C v.1	20110606	Product data sheet	-	-

## 10. Legal information

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Document status <sup>[1]</sup> <sup>[2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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